

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	42	("3146125" "3226256" "3873360" "3949121" "4248921" "4391742" "4411980" "4416914" "4756756" "4759970" "4906687" "5158645" "5922397" "5989653" "6051645" "6379569").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 16:35
S2	2	"5218168".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 16:37
S3	10	S1 and metal near oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:01
S4	7	S1 and resin near5 mixture	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:05
S5	2	S1 and resin near5 alkyd	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:07
S6	14231	(Paste ink) and resin near5 alkyd	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:08
S7	700	(Paste ink) and resin near5 alkyd and lithographic near printing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:08
S8	192	(Paste ink) and resin near5 alkyd and lithographic near printing and (polyamide amide) and nylon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:10

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S9	25	(Paste ink) and (resin near5 alkyd) same nylon and lithographic near printing and (polyamide amide) and solvent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:15
S10	276	(Paste ink) and (resin near5 alkyd) same nylon and printing and (polyamide amide) and solvent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:15
S11	2	(Paste ink) and (resin near5 alkyd) same nylon and printing and (polyamide amide) and solvent and electroless near5 deposition	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:18
S12	112	(Paste ink) and (resin near5 alkyd) same nylon and printing and (polyamide amide) and solvent and metal near5 oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:18
S13	109	(Paste ink) and (resin near5 alkyd) same nylon and printing and (polyamide amide) and solvent and metal near5 oxide not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 18:26

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S1	0	("205"/70.ccls.) and (electrochemical near5 displacement)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:12
S2	28	("205"/\$.ccls.) and (electrochemical near5 displacement)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:15
S3	2029	("205"/\$.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:18
S4	18	("205"/70.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:16
S5	0	("205"/\$.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating)) and wafer and oxide and nitrite and titanium and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:19
S6	38	("205"/\$.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating)) and wafer and oxide and nitride and titanium and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:43
S7	2	("427"/97.9.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating)) and wafer and oxide and nitride and titanium and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:44
S8	2	("427"/97.9.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating)) and wafer and oxide and nitride and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:44

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S9	4	("427"/97.9.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating)) and wafer and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:56
S10	57	("4619887" "4692349" "5008217" "5019531").PN. OR ("5308796").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/22 13:46
S11	170	("427"/\$.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating)) and wafer and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:57
S12	143	("427"/\$.ccls.) and ((electrochemical near5 displacement) (immers\$4 near5 plating)) and wafer and copper and (dielectric oxide nitride)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/22 13:57
S13	3	("4083754" "4725339" "6582580").PN. OR ("6838116").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/22 14:22